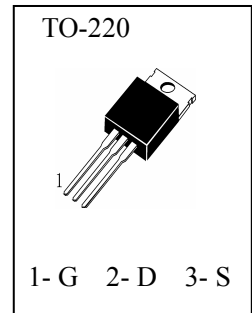




## N-Channel Enhancement Mode Field Effect Transistor

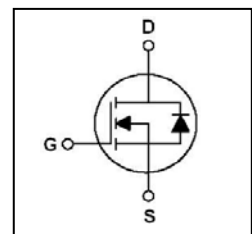
### General Description

These are N-Channel enhancement mode silicon gate power field effect transistors. They are advanced power MOSFETs designed, this advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode . These devices are well suited for low voltage applications such as audio amplifier, high efficiency switching DC/DC converters, and DC motor control.



### Features

- 17A, 100V,  $R_{DS(on)} < 70m\Omega @ V_{GS} = 10V$
- High density cell design for ultra low  $R_{Dson}$
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



### Maximum Ratings (Ta=25°C unless otherwise specified)

$T_{stg}$	Storage Temperature	-----	-55~150°C
$T_j$	Operating Junction Temperature	-----	150°C
$V_{DSS}$	Drain-Source Voltage	-----	100V
$V_{GSS}$	Gate-Source Voltage	-----	±20V
$I_D$	Drain Current (Continuous)( $T_c=25^\circ C$ )	-----	17A
$I_{DM}$	Pulsed Drain Current (Note 1)	-----	60A
$P_D$	Maximum Power Dissipation ( $T_c=25^\circ C$ )	-----	55W
	Derate Above 25°C	-----	0.43W/°C
$E_{AS}$	Pulsed Avalanche Energy (Note 2)	-----	250mJ
$I_{AR}$	Avalanche Current (Note 1)	-----	17A

### Thermal Characteristics

Symbol	Items	TO-220	Unit
Rthj-case	Thermal Resistance Junction-case	Max 2.27	°C/W
Rthj-amb	Thermal Resistance Junction-ambient	Max 62.5	°C/W

**Electrical Characteristics** (Ta=25°C unless otherwise specified)

Symbol	Items	Min.	Typ.	Max.	Unit	Conditions
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	100			V	I <sub>D</sub> =250μA, V <sub>GS</sub> =0V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current			1	μA	V <sub>DS</sub> =100V, V <sub>GS</sub> =0V
				10	μA	V <sub>DS</sub> =80V, V <sub>GS</sub> =0V, T <sub>j</sub> =150°C
I <sub>GSS</sub>	Gate – Body Leakage			±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> =0V
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	2.0		4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> =250μA
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance			80	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =8.5A
<b>Dynamic Characteristics and Switching Characteristics(Note 3)</b>						
C <sub>iss</sub>	Input Capacitance		1350		pF	V <sub>DS</sub> = 25 V, V <sub>GS</sub> = 0V, f = 1.0 MHz
C <sub>oss</sub>	Output Capacitance		240		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance		180		pF	
t <sub>d(on)</sub>	Turn - On Delay Time		13.8		nS	V <sub>DD</sub> = 30V, I <sub>D</sub> =2A, V <sub>GS</sub> = 10 V R <sub>G</sub> = 2.5 Ω (Note 4,5)
t <sub>r</sub>	Rise Time		9.3		nS	
t <sub>d(off)</sub>	Turn - Off Delay Time		43.8		nS	
t <sub>f</sub>	Fall Time		11.4		nS	
Q <sub>g</sub>	Total Gate Charge		31		nC	V <sub>DS</sub> =30V, I <sub>D</sub> =3A, V <sub>GS</sub> = 10 V (Note 4,5)
Q <sub>gs</sub>	Gate–Source Charge		6.4		nC	
Q <sub>gd</sub>	Gate–Drain Charge		9.4		nC	
<b>Drain-Source Diode Characteristics and Maximun Ratings</b>						
I <sub>S</sub>	Continuous Source–Drain Diode Forward Current			17	A	
I <sub>SM</sub>	Pulsed Drain-Source Diode Forward Current			60	A	
V <sub>SD</sub>	Source–Drain Diode Forward On–Voltage			1.2	V	I <sub>S</sub> =9A, V <sub>GS</sub> =0

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. L=0.5mH, V<sub>G</sub>=10V, V<sub>DD</sub>=50V, R<sub>G</sub>=25 Ω, T<sub>J</sub>=25°C
3. Guaranteed by design, not subject to production
4. Pulse Test: Pulse width≤300μS, Duty Cycle≤2%
5. Essentially independent of operating temperature



## Typical Characteristics

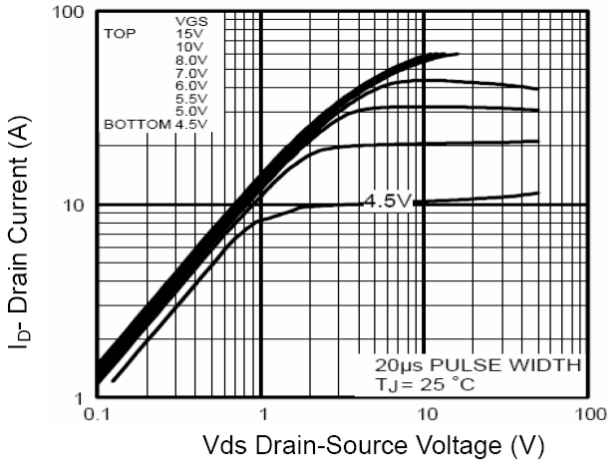


Figure 1 Output Characteristics

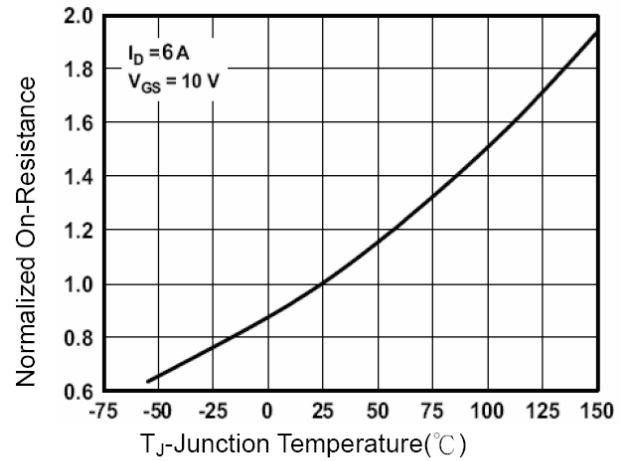


Figure 4  $R_{dson}$ -Junction Temperature

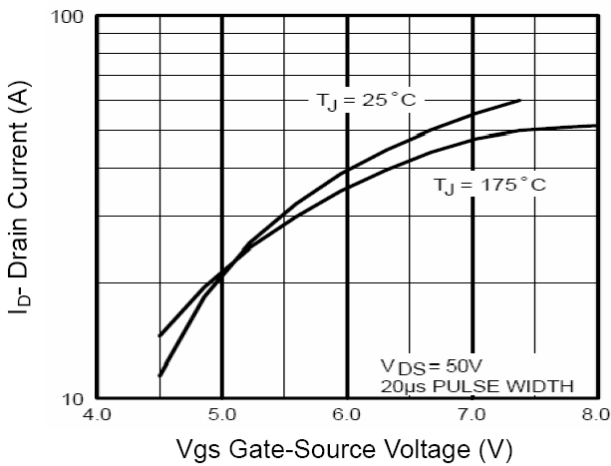


Figure 2 Transfer Characteristics

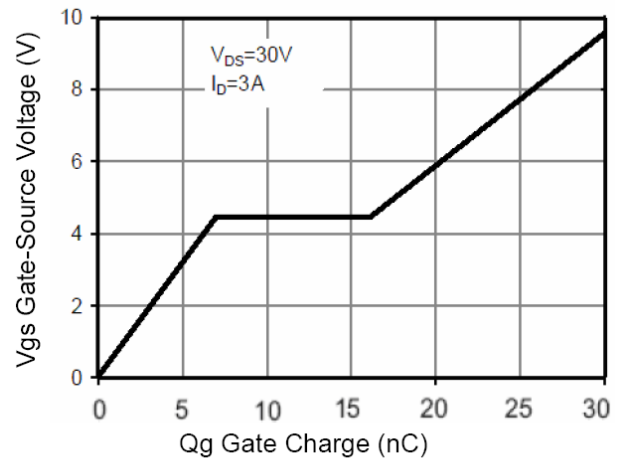


Figure 5 Gate Charge

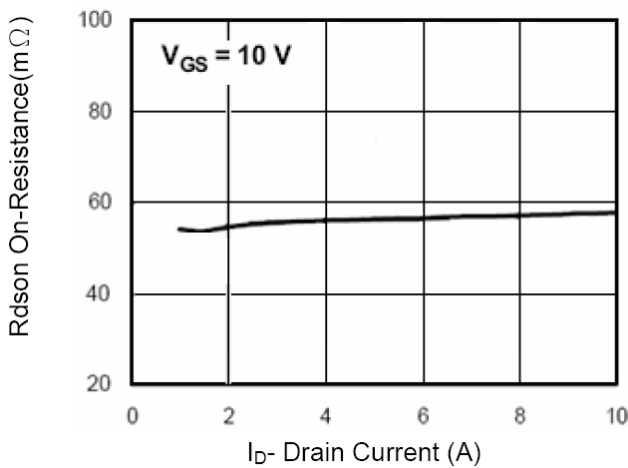


Figure 3  $R_{dson}$ - Drain Current

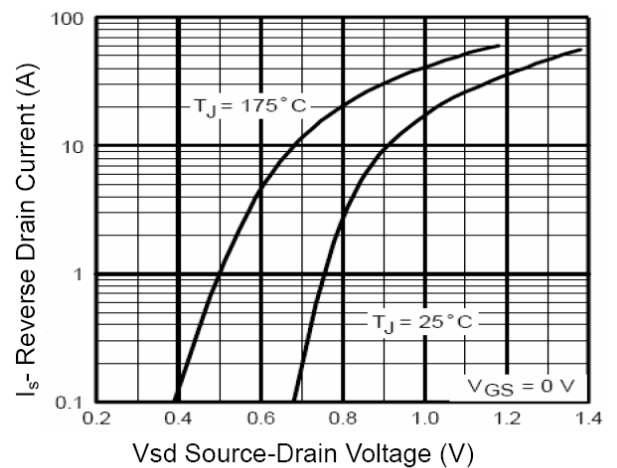


Figure 6 Source- Drain Diode Forward



Typical Characteristics

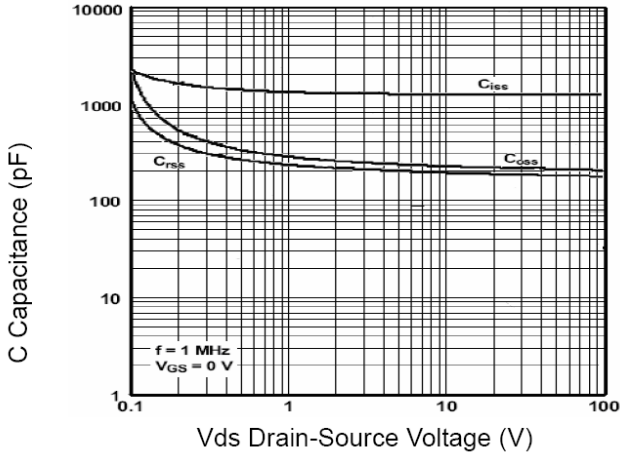


Figure 7 Capacitance vs Vds

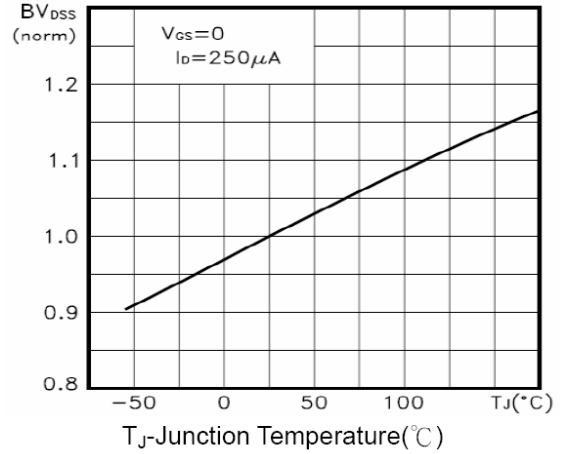


Figure 9  $BV_{DSS}$  vs Junction Temperature

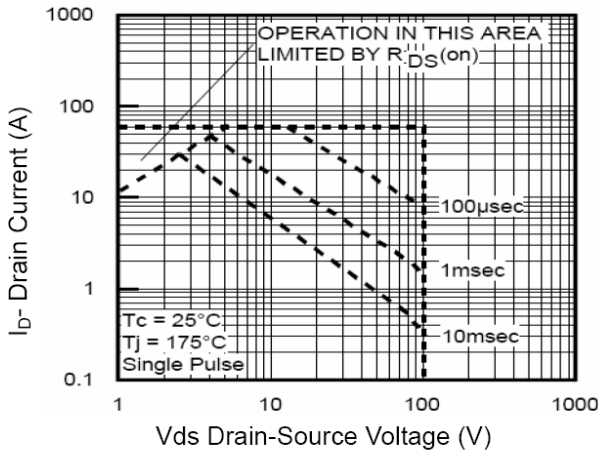


Figure 8 Safe Operation Area

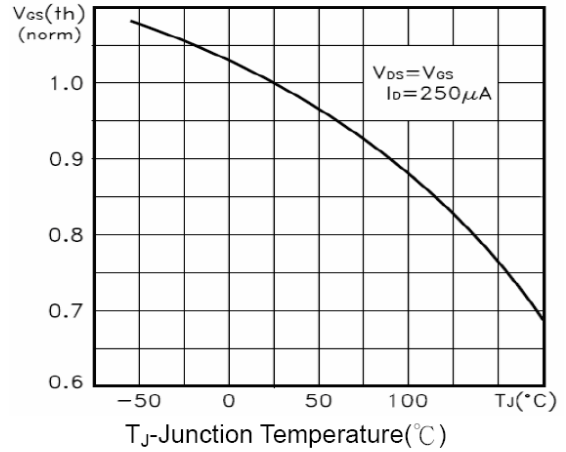


Figure 10  $V_{GS(th)}$  vs Junction Temperature

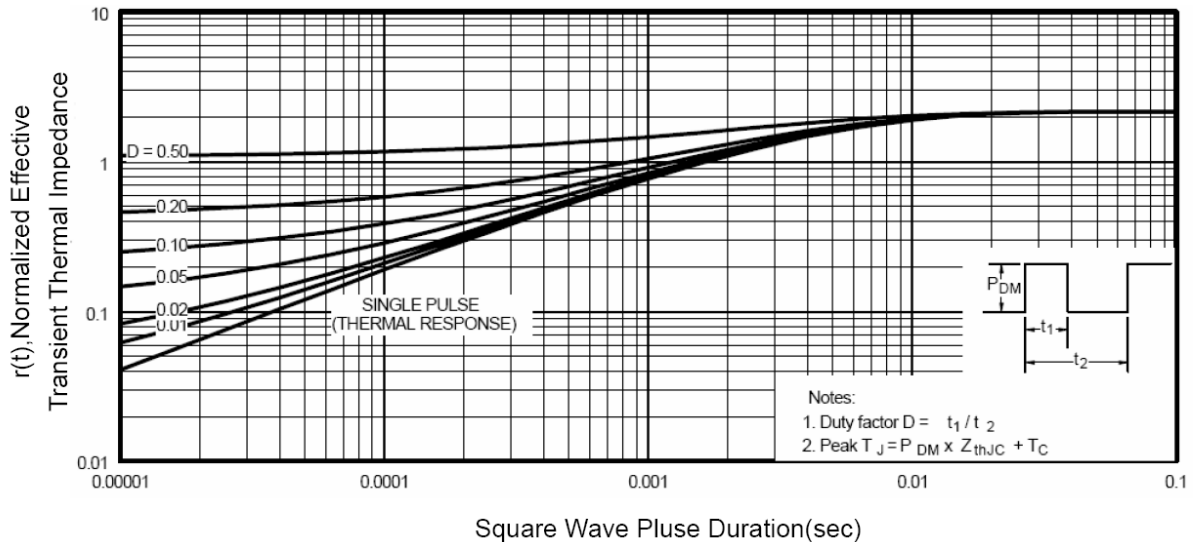


Figure 11 Normalized Maximum Transient Thermal Impedance



■ Typical Characteristics

Fig 12. Gate Charge Test Circuit & Waveform

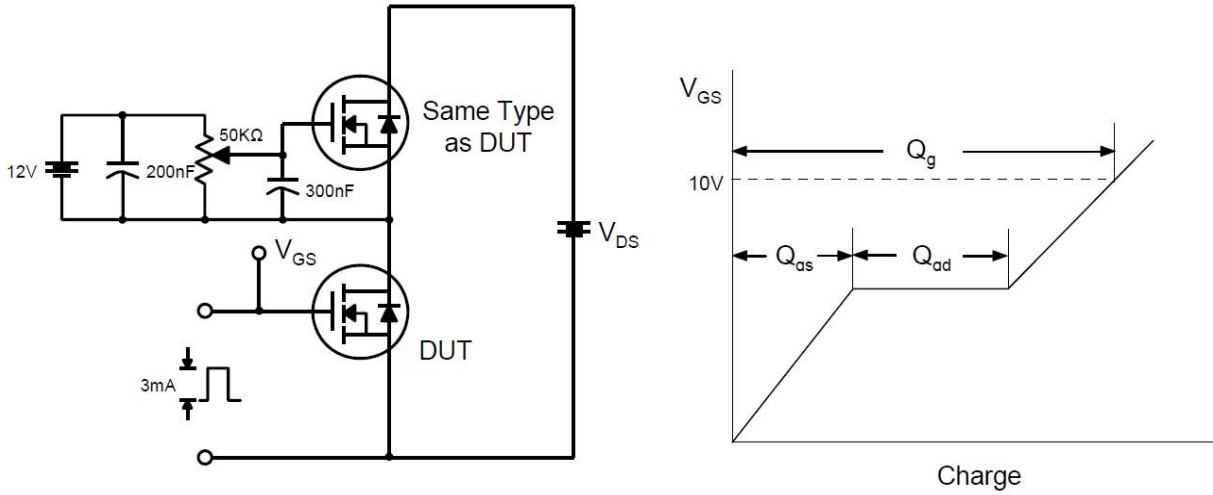


Fig 13. Resistive Switching Test Circuit & Waveforms

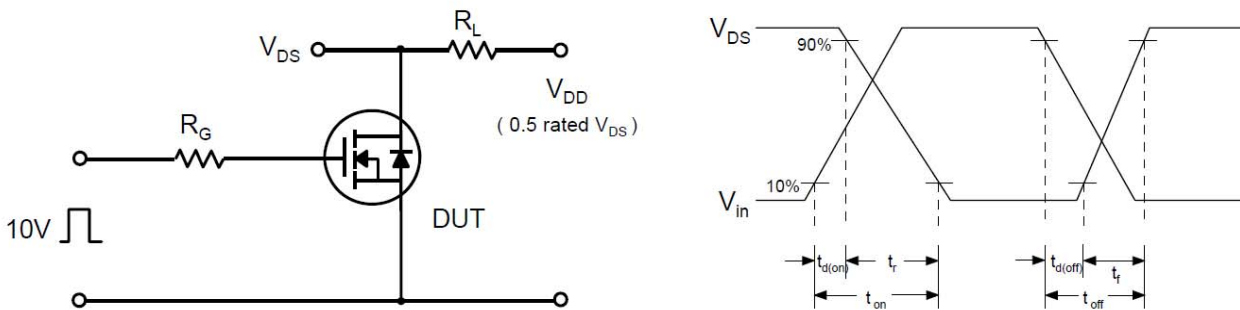
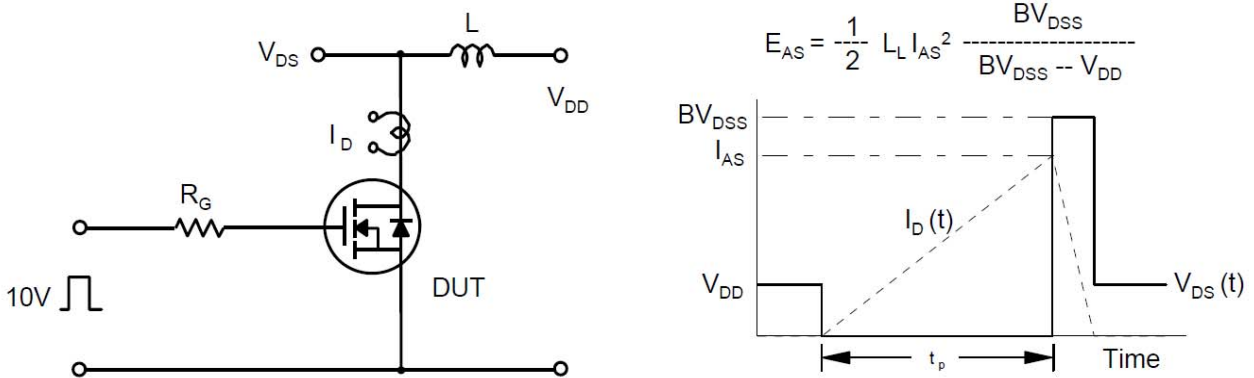


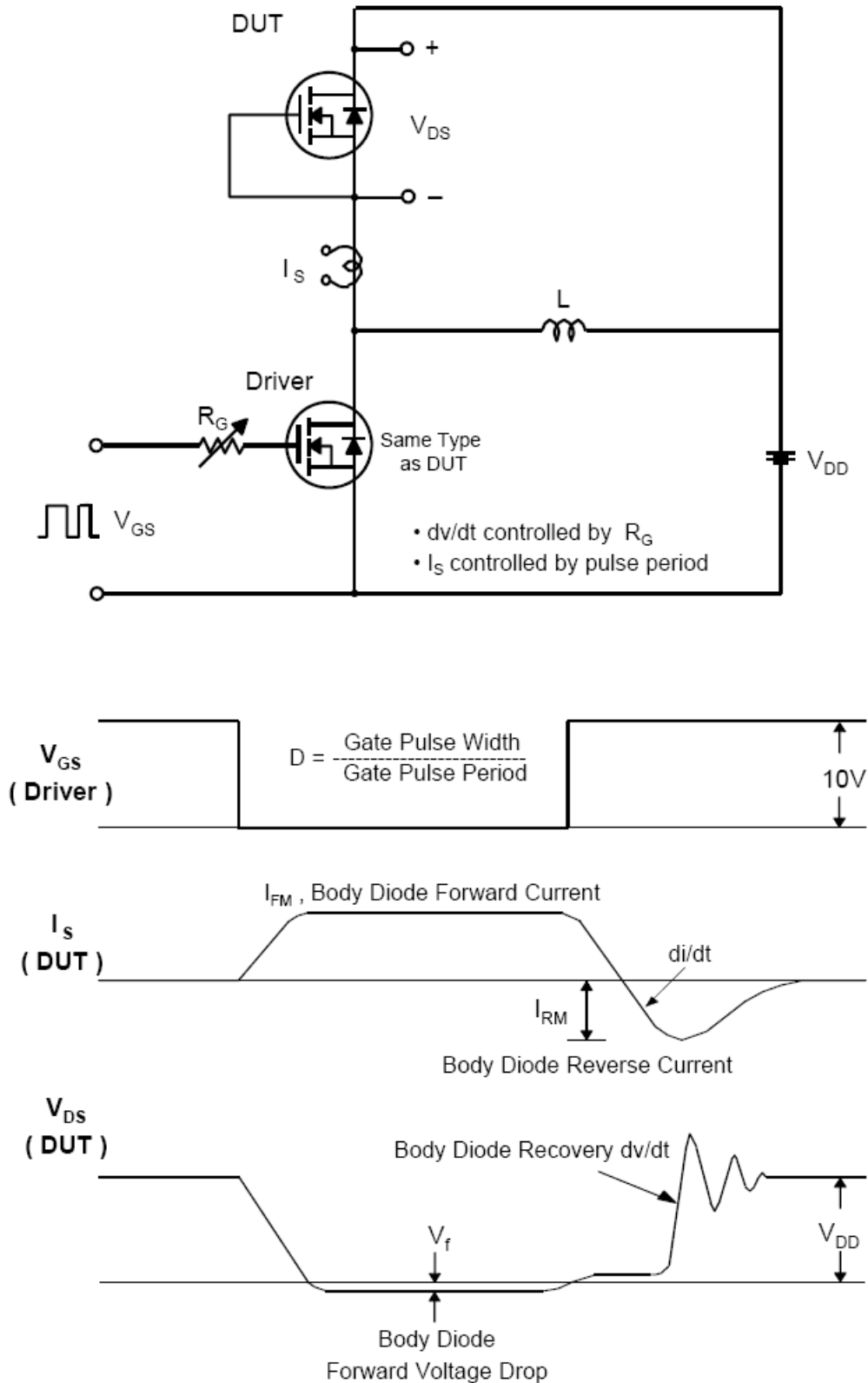
Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms





## Typical Characteristics

Fig 15. Peak Diode Recovery  $dv/dt$  Test Circuit & Waveforms





## Package Dimensions

